PCN Number:		20130312000					PCN Date:		03/12/2013	
Title: TS5A23157TDGSRQ1 MSL - CMS C1303041										
<b>Customer Contact:</b>		PCN Manager			Phone:	+1(214)	480-6	Dept:	Qua	ality Services
Change Type:										
Asse	Assembly Site			Assembly Process				Assembly Materials		
Desi	Design			Electrical Specification				Mechanical Specification		
Test Site				Packing/Shipping/Labeling				Test Process		
Wafer Bump Site				Wafer I	Wafer Bump Material			Wafer Bump Process		
Wafer Fab Site			Wafer Fab Materials				Wafer Fab Process			

## **PCN Details**

## **Description of Change:**

Change the pack method from the current moisture sensitivity level 1 (MSL1) to level 3 (MSL3). Devices will now be packed in moisture barrier bag, include a desiccant and humidity indicator card (HIC). The device box label will reflect the change from MSL1 to MSL3.

## **Reason for Change:**

Incorrect pack method was used.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Positive impact. Devices will now be packed correctly.

Changes to product identification resulting from this PCN:

The moisture sensitivity level on the box label will change from MSL1@360C to MSL3@260C.

**Product Affected:** 

TS5A23157TDGSRQ1

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com